



## N-Channel Enhancement-Mode Vertical DMOS FETs

### Ordering Information

BV <sub>DSS</sub> / BV <sub>DGS</sub>	R <sub>DS(ON)</sub> (max)	I <sub>D(ON)</sub> (min)	Order Number / Package	
			TO-243AA*	Die**
350V	6.0Ω	1.0A	TN2435N8	TN2435NW

Product marking for TO-243AA:

**TN4D\***

where \* = 2-week alpha date code

\* Same as SOT-89. Product supplied on 2000 piece carrier tape reels.

\*\* Die in wafer form.

### Features

- High input impedance
- Low input capacitance
- Fast switching speeds
- Free from secondary breakdown
- Low input and output leakage
- Complementary N- and P-channel devices

### Applications

- Logic level interfaces
- Solid state relays
- Power Management
- Analog switches
- Ringers
- Telecom switches

### Absolute Maximum Ratings

Drain-to-Source Voltage	BV <sub>DSS</sub>
Drain-to-Gate Voltage	BV <sub>DGS</sub>
Gate-to-Source Voltage	± 20V
Operating and Storage Temperature	-55°C to +150°C
Soldering Temperature*	300°C

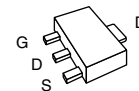
\* Distance of 1.6 mm from case for 10 seconds.

### Low Threshold DMOS Technology

These low threshold enhancement-mode (normally-off) transistors utilize a vertical DMOS structure and Supertex's well-proven silicon-gate manufacturing process. This combination produces devices with the power handling capabilities of bipolar transistors and with the high input impedance and positive temperature coefficient inherent in MOS devices. Characteristic of all MOS structures, these devices are free from thermal runaway and thermally induced secondary breakdown.

Supertex vertical DMOS FETs are ideally suited to a wide range of switching and amplifying applications where very low threshold voltage, high breakdown voltage, high input impedance, low input capacitance, and fast switching speeds are desired.

### Package Option



TO-243AA  
(SOT-89)

Note: See Package Outline section for dimensions.

# Thermal Characteristics

Package	I <sub>D</sub> (continuous)*	I <sub>D</sub> (pulsed)	Power Dissipation @ T <sub>A</sub> = 25°C	θ <sub>Jc</sub> °C/W	θ <sub>Ja</sub> °C/W	I <sub>DR</sub> *	I <sub>DRM</sub>
TO-243AA	365mA	1.8A	1.6W†	15	78†	365mA	1.8A

\* I<sub>D</sub> (continuous) is limited by max rated T<sub>J</sub>

† Mounted on FR5 board, 25mm x 25mm x 1.57mm. Significant P<sub>D</sub> increase possible on ceramic substrate.

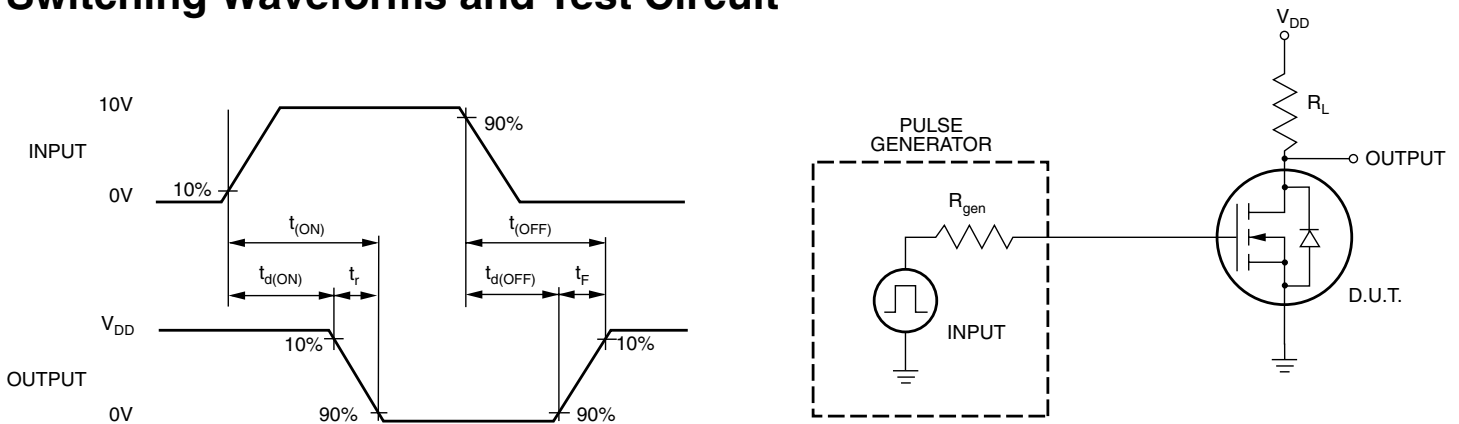
# Electrical Characteristics (@ 25°C unless otherwise specified)

Symbol	Parameter	Min	Typ	Max	Unit	Conditions
BV <sub>DSS</sub>	Drain-to-Source Breakdown Voltage	350			V	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA
V <sub>GS(th)</sub>	Gate Threshold Voltage	0.8			V	V <sub>GS</sub> = V <sub>DS</sub> , I <sub>D</sub> = 1.0mA
ΔV <sub>GS(th)</sub>	Change in V <sub>GS(th)</sub> with Temperature			-5.5	mV/°C	V <sub>GS</sub> = V <sub>DS</sub> , I <sub>D</sub> = 1.0mA
I <sub>GSS</sub>	Gate Body Leakage			100	nA	V <sub>GS</sub> = ± 20V, V <sub>DS</sub> = 0V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current			10	μA	V <sub>GS</sub> = 0V, V <sub>DS</sub> = Max Rating
				1.0	mA	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 0.8 Max Rating T <sub>A</sub> = 125°C
I <sub>D(ON)</sub>	ON-State Drain Current	0.5			A	V <sub>GS</sub> = 4.5V, V <sub>DS</sub> = 25V
		1.0				V <sub>GS</sub> = 10V, V <sub>DS</sub> = 25V
R <sub>DS(ON)</sub>	Static Drain-to Source ON-State Resistance			15.0	Ω	V <sub>GS</sub> = 3.0V, I <sub>D</sub> = 150mA
				10.0		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 250mA
				6.0		V <sub>GS</sub> = 10V, I <sub>D</sub> = 750mA
ΔR <sub>DS(ON)</sub>	Change in R <sub>DS(ON)</sub> with Temperature			1.7	%/°C	V <sub>GS</sub> = 10V, I <sub>D</sub> = 750mA
G <sub>FS</sub>	Forward Transconductance	125			m <sup>2</sup>	V <sub>DS</sub> = 25V, I <sub>D</sub> = 350mA
C <sub>ISS</sub>	Input Capacitance		125	200	pF	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 25V f = 1.0MHz
C <sub>OSS</sub>	Common Source Output Capacitance		25	70		
C <sub>RSS</sub>	Reverse Transfer Capacitance		8	25		
t <sub>d(ON)</sub>	Turn-ON Delay Time		5	20	ns	V <sub>DD</sub> = 25V, I <sub>D</sub> = 750mA R <sub>GEN</sub> = 25Ω
t <sub>r</sub>	Rise Time		10	20		
t <sub>d(OFF)</sub>	Turn-OFF Delay Time		28	40		
t <sub>f</sub>	Fall Time		10	30		
V <sub>SD</sub>	Diode Forward Voltage Drop			1.5	V	V <sub>GS</sub> = 0V, I <sub>SD</sub> = 750mA
t <sub>rr</sub>	Reverse Recovery Time		300		ns	V <sub>GS</sub> = 0V, I <sub>SD</sub> = 750mA

**Notes:**

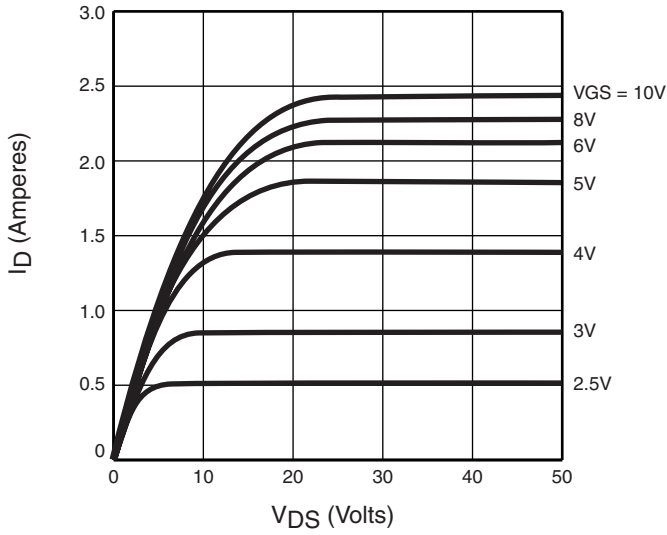
- 1.All D.C. parameters 100% tested at 25°C unless otherwise stated. (Pulse test: 300μs pulse, 2% duty cycle.)
- 2.All A.C. parameters sample tested.

# Switching Waveforms and Test Circuit

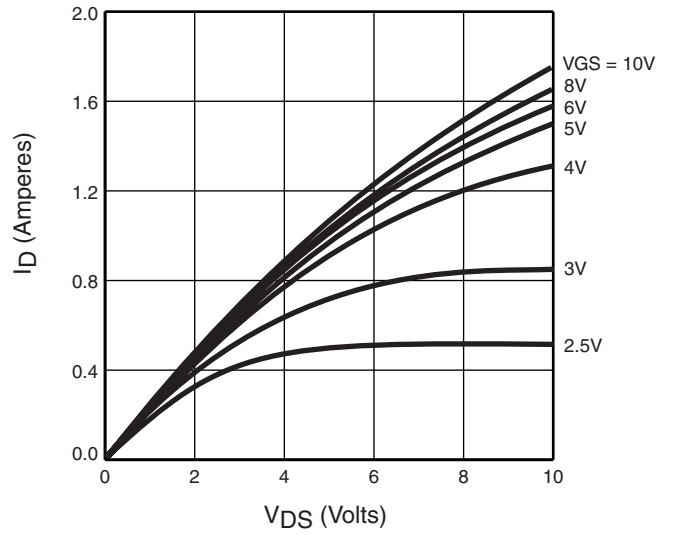


# Typical Performance Curves

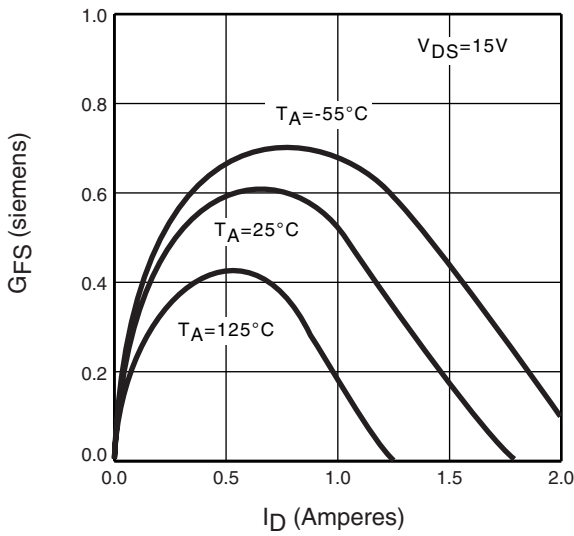
Output Characteristics



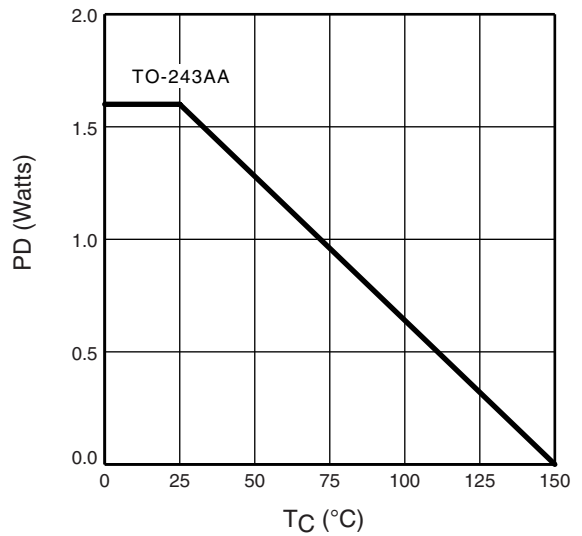
Saturation Characteristics



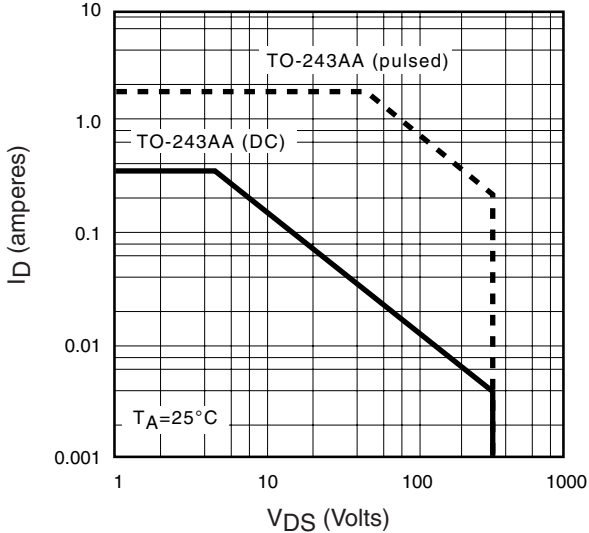
Transconductance vs. Drain Current



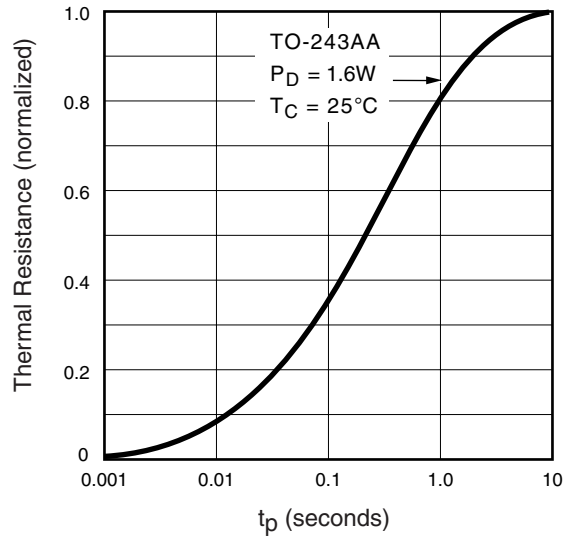
Power Dissipation vs. Case Temperature



Maximum Rated Safe Operating Area

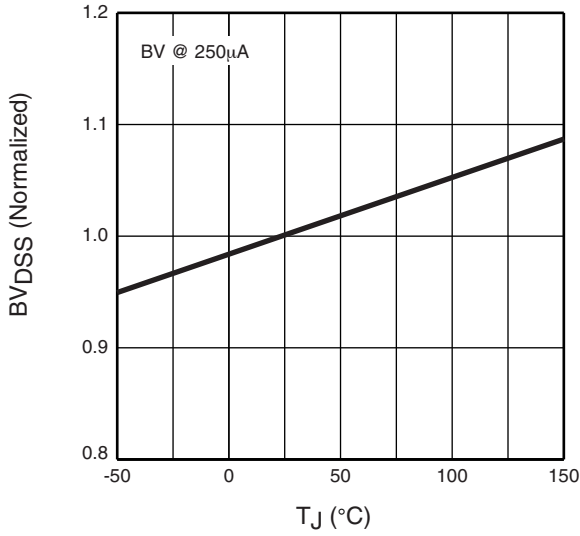


Thermal Response Characteristics

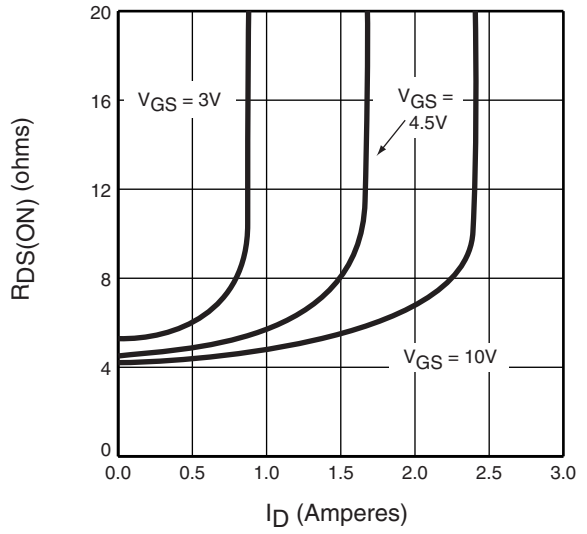


# Typical Performance Curves

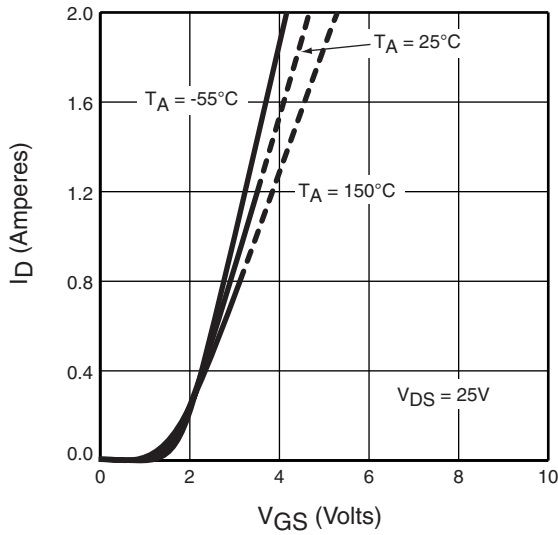
BV<sub>DSS</sub> Variation with Temperature



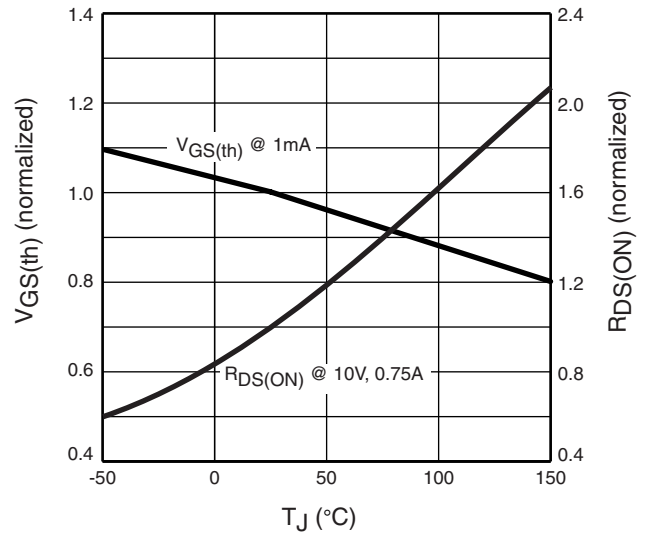
On Resistance vs. Drain Current



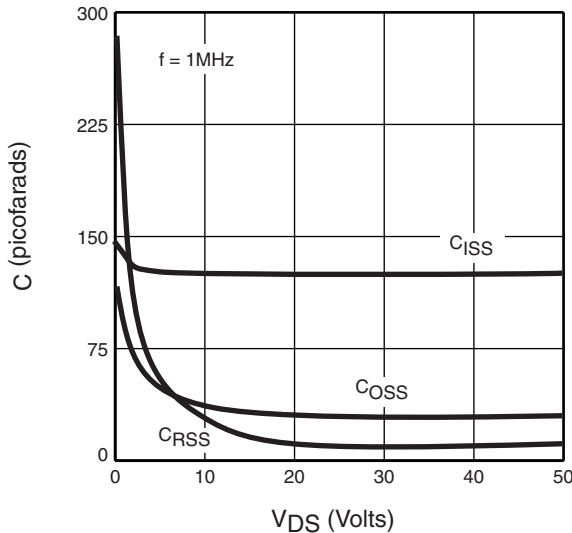
Transfer Characteristics



V<sub>GS(th)</sub> and R<sub>DS(ON)</sub> w/ Temperature



Capacitance vs. Drain Source Voltage



Gate Drive Dynamic Characteristics

